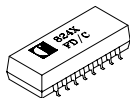
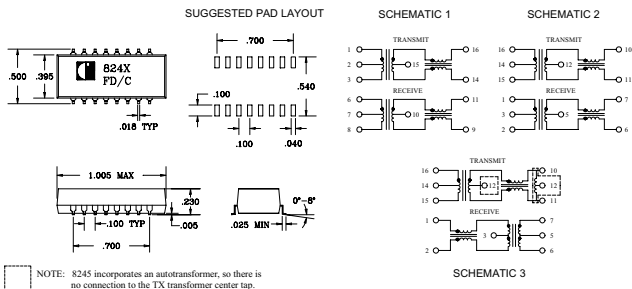


- Meets all IEEE 802.3 and ANSI X3.263 standards including 350 μ H OCL with 8mA bias
- IC grade transfer-molded package suitable for reflow soldering temperatures up to 235°C
- Applicable with AMD, Kendin Semiconductor and Quality Semiconductor transceivers



MECHANICAL AND SCHEMATIC (All dimensions in inches)



ELECTRICAL SPECIFICATIONS @ 25°C

Part Number	Turns Ratio ($\pm 5\%$)		Insertion Loss 100 MHz - 100 MHz (dB MAX)	Return Loss (dB MIN)			Crosstalk (dB MIN)			Schematic	Hipot (Vrms MIN)
	Receive	Transmit		30 MHz	60 MHz	80 MHz	30 MHz	60 MHz	100 MHz		
8240	1:1	$\sqrt{2}$:1	-1.0	-16	-12	-10	-45	-38	-34	1	1500
8241	1:1	$\sqrt{2}$:1	-1.0	-16	-12	-10	-45	-38	-34	2	1500
8242	1:1	$\sqrt{2}$:1	-1.0	-16	-12	-10	-45	-38	-34	1	1500
8243	1:1	$\sqrt{2}$:1	-1.0	-16	-12	-10	-45	-38	-34	3	1500
8244	1:1	1.25:1	-1.0	-16	-12	-10	-45	-38	-34	1	1500
8245	1:1	1: $\sqrt{2}$	-2.0	-18	-12	-11	-45	-38	-34	3	1500
8246	1:1	$\sqrt{2}$:1	-1.0	-16	-12	-10	-45	-38	-34	1	1500
8247	1:1	1: $\sqrt{2}$	-2.0	-16	-11	-10	-45	-38	-34	3	1500